

REMARKS

Claims 1 to 20 are currently pending in the present application. Claims 11-20 have been added. No new matter has been added.

Claims 1-4, 6-7 and 9-10 stand rejected by the Office Action under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent No. 6,510,195 to Chappo et al. (hereinafter “Chappo”). Applicants respectfully submit that Chappo does not expressly or inherently disclose all of the elements set forth in independent claims 1 and 10. Thus, Chappo does not anticipate claims 1 or 10, or claims 2-4, 6-7 and 9, which depend from claim 1.

Claims 1-4, 6-7 and 9-10 include the feature of the module being mounted on the same side of the substrate as the array of sensor elements. Chappo describes a solid state x-ray radiation detector that provides sensors 52 connected to one side of a substrate 58 by bumps 56 and signal processing electronics 60 on an opposite side of the substrate as shown in FIG. 12 which is relied upon by the Office Action:

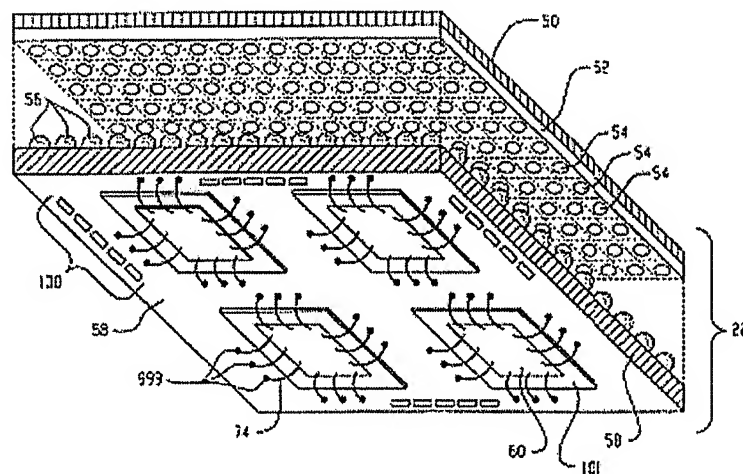


Fig. 12

Chappo does not disclose or suggest the module being mounted on the same side of the substrate as the array of sensor elements, as in claims 1-4, 6-7 and 9-10. Claims 11-20

also include the feature of the module being mounted on the same side of the substrate as the array of sensor elements.

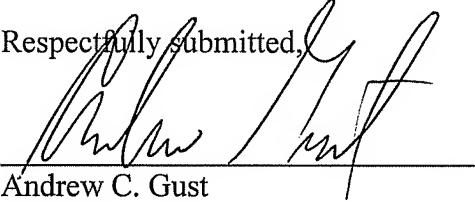
Claims 5 and 8 stand rejected under 35 U.S.C. 103(a) as being unpatentable over Chappo in view of U.S. Patent No. 6,403,964 to Kyyhkynen. Claims 5 and 8 depend from claim 1 and include the feature of the module being mounted on the same side of the substrate as the array of sensor elements. As discussed above, Chappo does not disclose or suggest this feature. Kyyhkynen is directed to a modular imaging apparatus that uses imaging tiles which can be positioned on a support structure, such as through use of nuts and screws. (Kyyhkynen col. 12, lines 7-12). Kyyhkynen also does not disclose or suggest the feature of the module being mounted on the same side of the substrate as the array of sensor elements.

In view of the foregoing, Applicants respectfully submit that the specification, the drawings and all claims presented in this application are currently in condition for allowance. Accordingly, Applicants respectfully request favorable consideration and that this application be passed to allowance. Should any changes to the claims and/or specification be deemed necessary to place the application in condition for allowance, the Examiner is respectfully requested to contact the undersigned to discuss the same.

Dated: _____

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Respectfully submitted,



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